

Technical Data Sheet

1.6mm round Subminiature Side Looking Infrared LED EAISV3026A0

Features

- Peak wavelength $\lambda_p=940\text{nm}$.
- Low forward voltage.
- Compatible with infrared and vapor phase reflow solder process.
- Package in 8mm tape on 7" diameter reels.
- Pb free
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm)

Description

- EAISV3026A0 is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with flat top view lens. The device is spectrally matched with silicon photodiode and phototransistor.

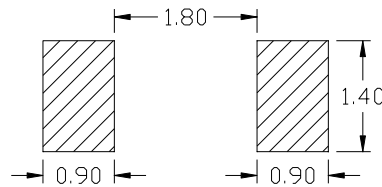
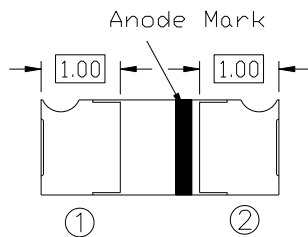
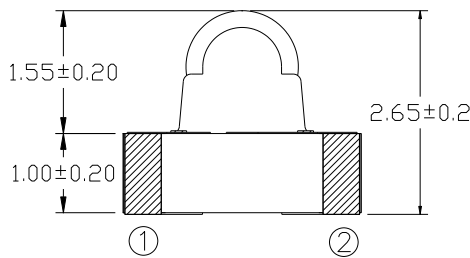
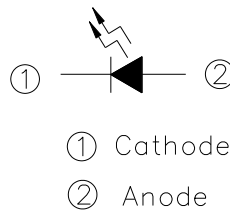
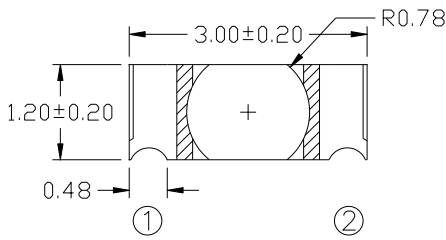
Applications

- Infrared applied system

Device Selection Guide

Device No.	Chip Material	Lens Color
EAISV3026A0	GaAlAs	Water clear

Package Dimensions



Recommended Soldering Pattern
for Side Looker

- Notes:** 1.All dimensions are in millimeters
2.Tolerances unless dimensions $\pm 0.1\text{mm}$

Absolute Maximum Ratings ($T_a=25^\circ\text{C}$)

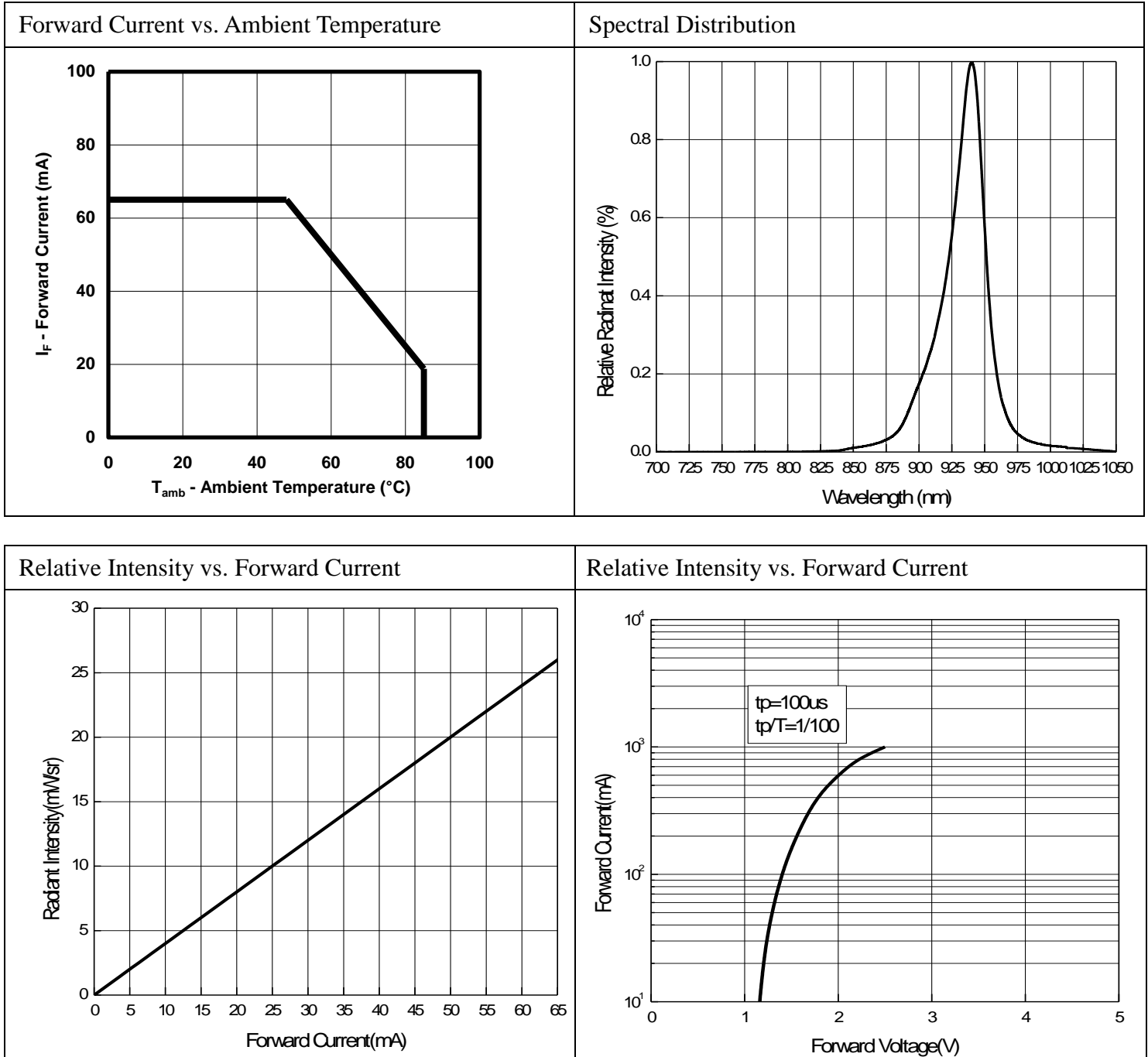
Parameter	Symbol	Rating	Unit
Continuous Forward Current	I_F	65	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-40 ~ +85	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 ~ +100	$^\circ\text{C}$
Soldering Temperature *1	T_{sol}	260	$^\circ\text{C}$
Power Dissipation at(or below) 25 $^\circ\text{C}$ Free Air Temperature	P_d	100	mW

Notes: *1:Soldering time ≤ 5 seconds.

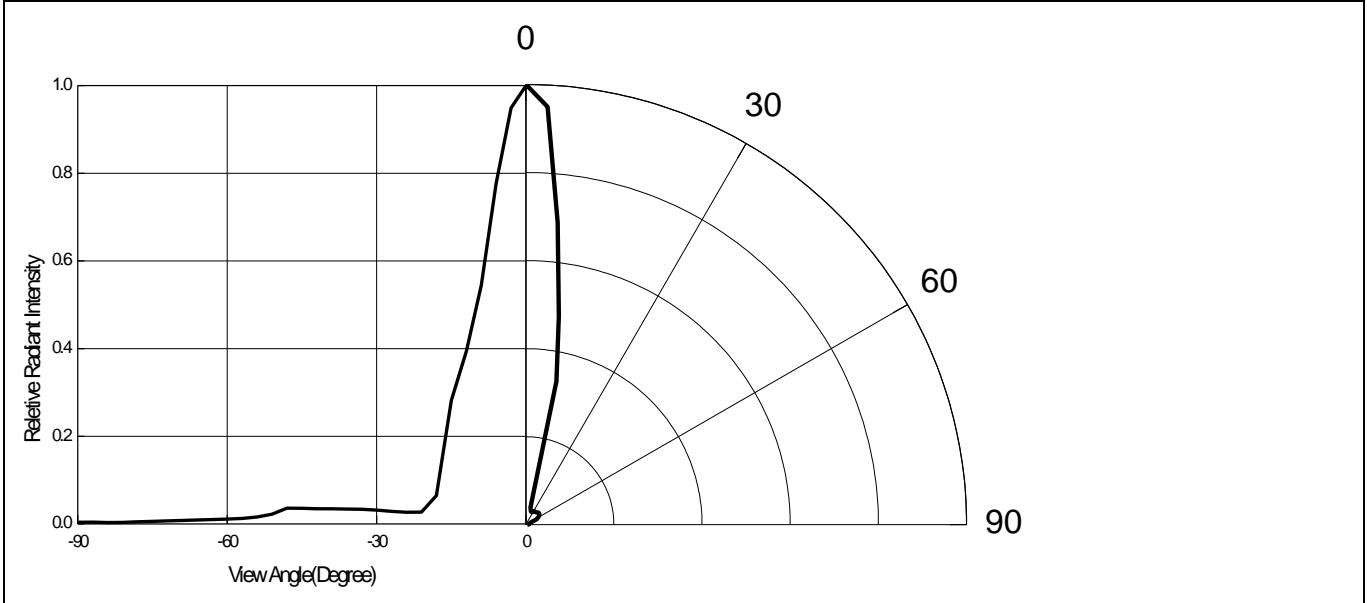
Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Radiant Intensity	I _e	4.0	8.0	--	mW /sr	I _F =20mA
		--	40	--		I _F =100mA Pulse Width ≤ 100μ s ,Duty ≤ 1%
Peak Wavelength	λ _p	920	940	960	nm	I _F =100mA
Spectral Bandwidth	Δλ	--	30	--	nm	I _F =100mA
Forward Voltage	V _F	--	1.25	1.50	V	I _F =20mA
		--	1.40	1.80		I _F =100mA Pulse Width ≤ 100μ s ,Duty ≤ 1%
Reverse Current	I _R	--	--	10	μ A	V _R =5V
View Angle	2θ _{1/2}	--	20	--	deg	I _F =20mA

Typical Electrical/Optical/Characteristics Curves



Relative Radiant Intensity vs. Angular Displacement



Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.

2.3 The LEDs should be used within a year.

2.4 After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.

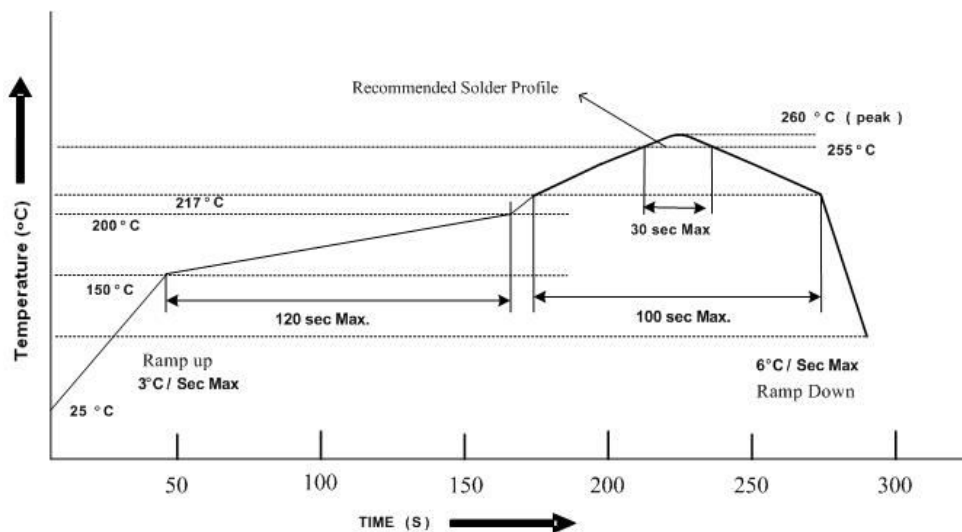
2.5 The LEDs should be used within 168 hours (7 days) after opening the package

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for Min. 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

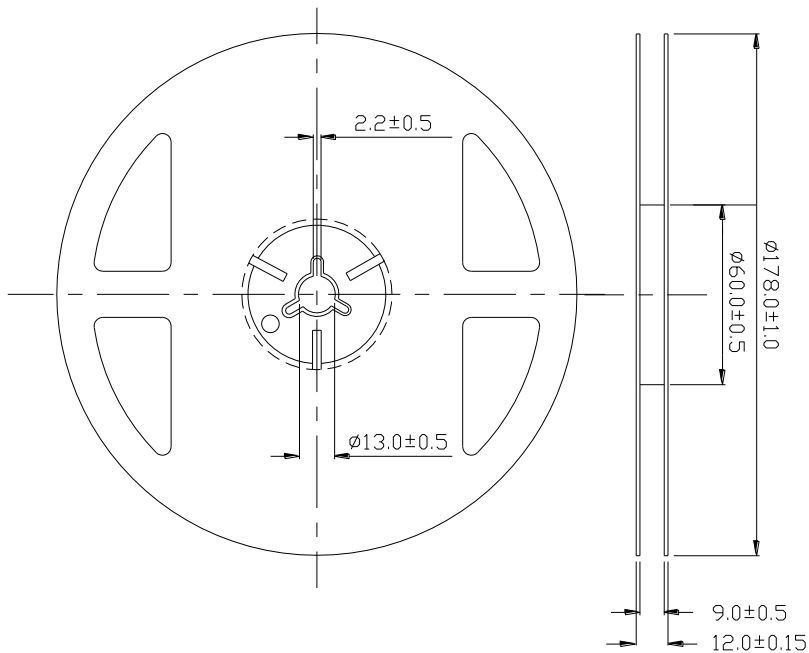
Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

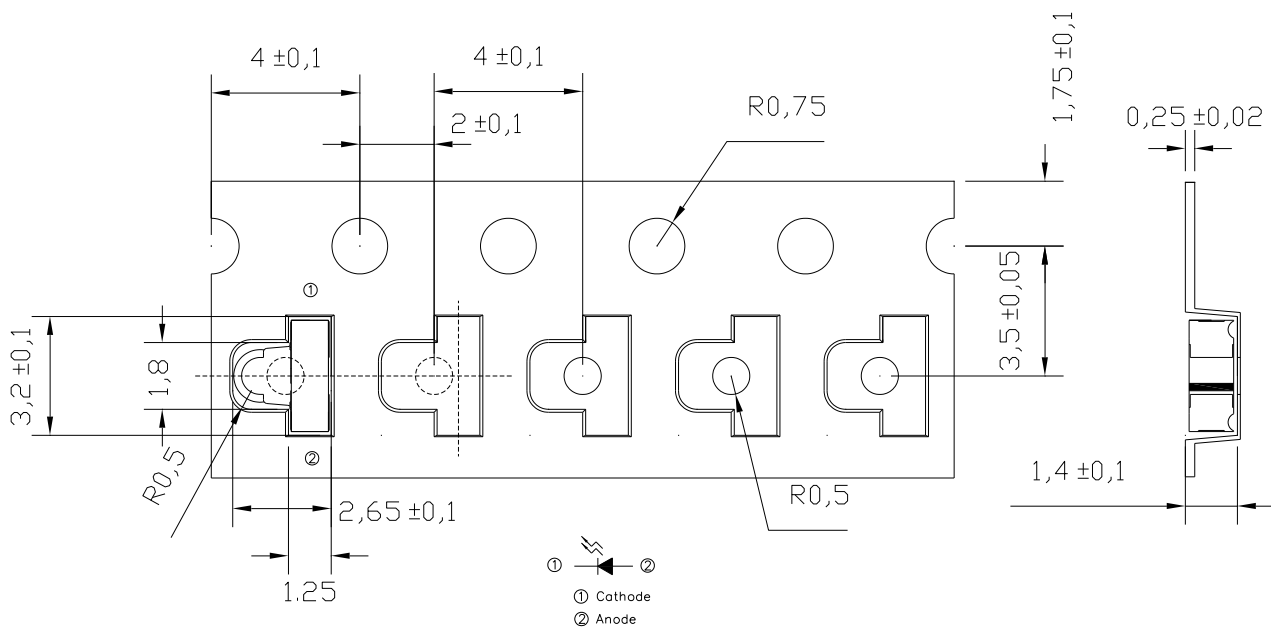


Package Dimensions



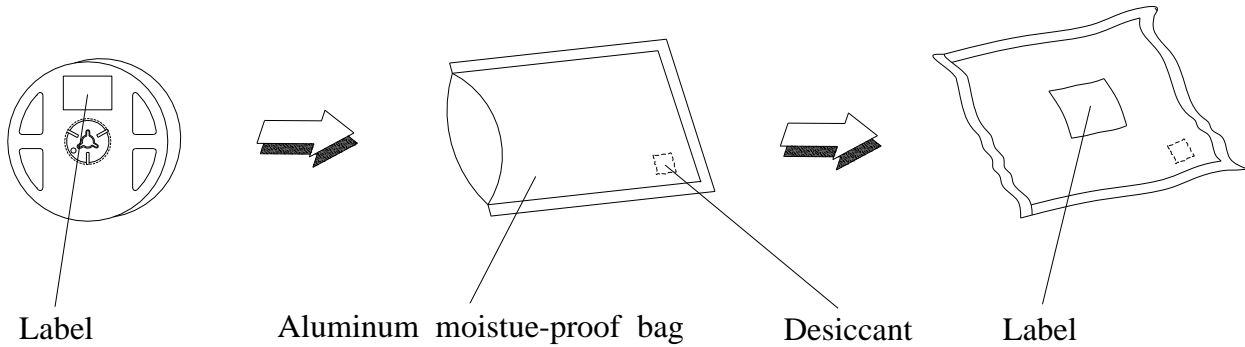
Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Carrier Tape Dimensions:(Quantity: 1500pcs/reel)

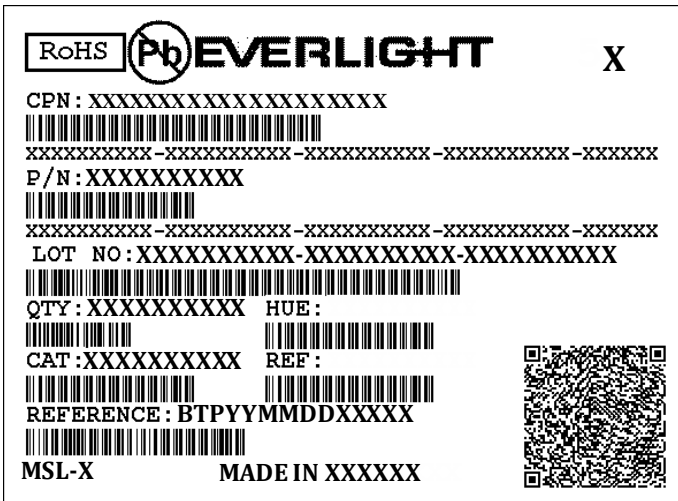


Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Packing Procedure



Label Form Specification



CPN: Customer's Production Number
 P/N : Production Number
 QTY: Packing Quantity
 CAT: Ranks
 HUE: Peak Wavelength
 REF: Reference
 LOT No: Lot Number
 MADE IN TAIWAN: Production Place

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3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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